



# TouchCore Family

SS-TouchCore1.0-V1.9



## Spec. Sheet of **TouchCore1.0** Family

### Digital-type / Capacitive Touch Sensor Engine

V1.9

June 2008

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## 1. What is TouchCore?

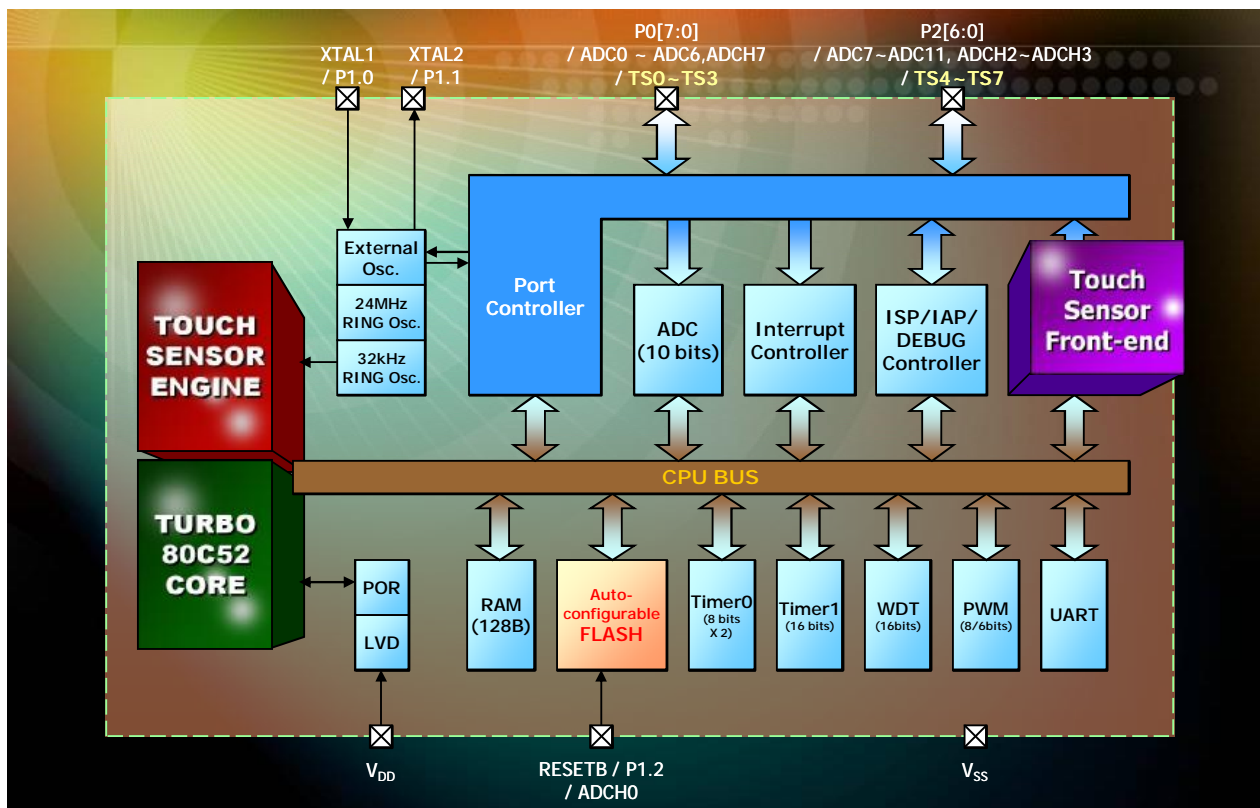


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*TouchCore1.0 Family*

[3]

## 2. Block Diagram



## 3. Features

### u Digital-type Touch Sensor Engine

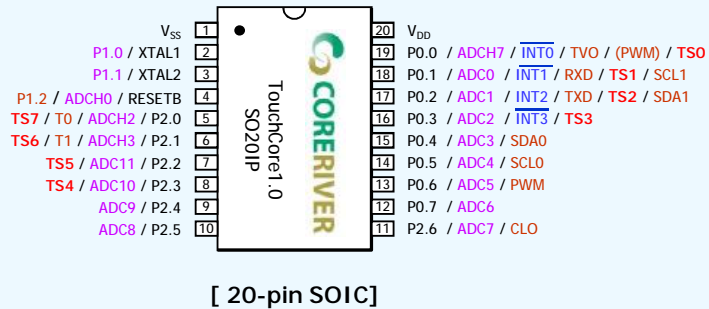
- ü Capacitive Touch Sensor Engine with Auto-configurable Flash Memory

- u 4kB FLASH (Including 256B EEPROM)
- u Operating Voltage : 1.8V ~ 5.5V
- u Operating Temperature : -20°C ~ +85°C
- u Operating Frequency
  - ü Max. 23MHz @  $V_{DD} = 5.0V$
  - ü Max. 12MHz @  $V_{DD} = 3.3V$
- u Max. Programmable 18 Output Pins
  - ü Push-Pull Output
- u LVD (Low Voltage Detector)
- u Internal RING Oscillator
  - ü Max. 12MHz @ 5.0V
  - ü 4MHz @ 2.7V ~ 5.0V (+/-3%)
  - ü 32KHz @ 2.7V (+/-10%) (Low power 32KHz OSC)
- u Supporting ISP & IAP
- u Latch-up Protection Up to  $\pm 200mA$
- u E.S.D. Protection Up to
  - ü 6000V for Touch Sensor Pad
  - ü 2000V for normal I/O

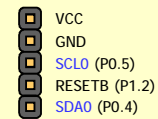
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- u Max. 8-channel TS (Touch Sensors)
  - u 2-channel I2C Slave (I2C Master/Slave, I2C Slave)
  - u 16-bit Programmable Watchdog Timer
  - u UART / PWM / Timer / I2C
  - u 16-channel 10-bit ADC
    - ü Max 100KSPS (@ $F_{ADC} = 8\text{ MHz}$ )
    - ü Programmable input clock frequency
  - u 14 Interrupt Sources
    - ü Timer0/1, WDT, LVD, ADC, UART, 2-I2C, ,PWM, TS
    - ü 4 External sources : both edge/level
    - ü Two-level interrupt priority
  - u Reset Sources
    - ü On-chip POR (Power-On-Reset)
    - ü LVD (Low Voltage Detector) Reset
    - ü WDT (Watchdog Timer) Reset
  - u Power Consumption
    - ü Typ. 6uA @  $V_{DD}=2.0V$  (SNAP Mode)
    - ü Typ. 1uA @  $V_{DD}=5.0V$  (All Clock OFF) (Changeable)
  - u Packages
    - ü 20-pin Packages : Wide-SOIC / QFN
    - ü 8-pin Package : SOIC
- TouchCore1.0 Family** [5]

## 4. Pin Configurations (1 of 2)

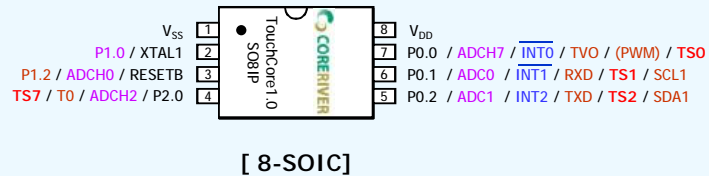


### [ISP Pin Configuration]

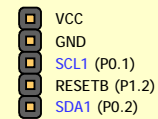


### [Ordering Information]

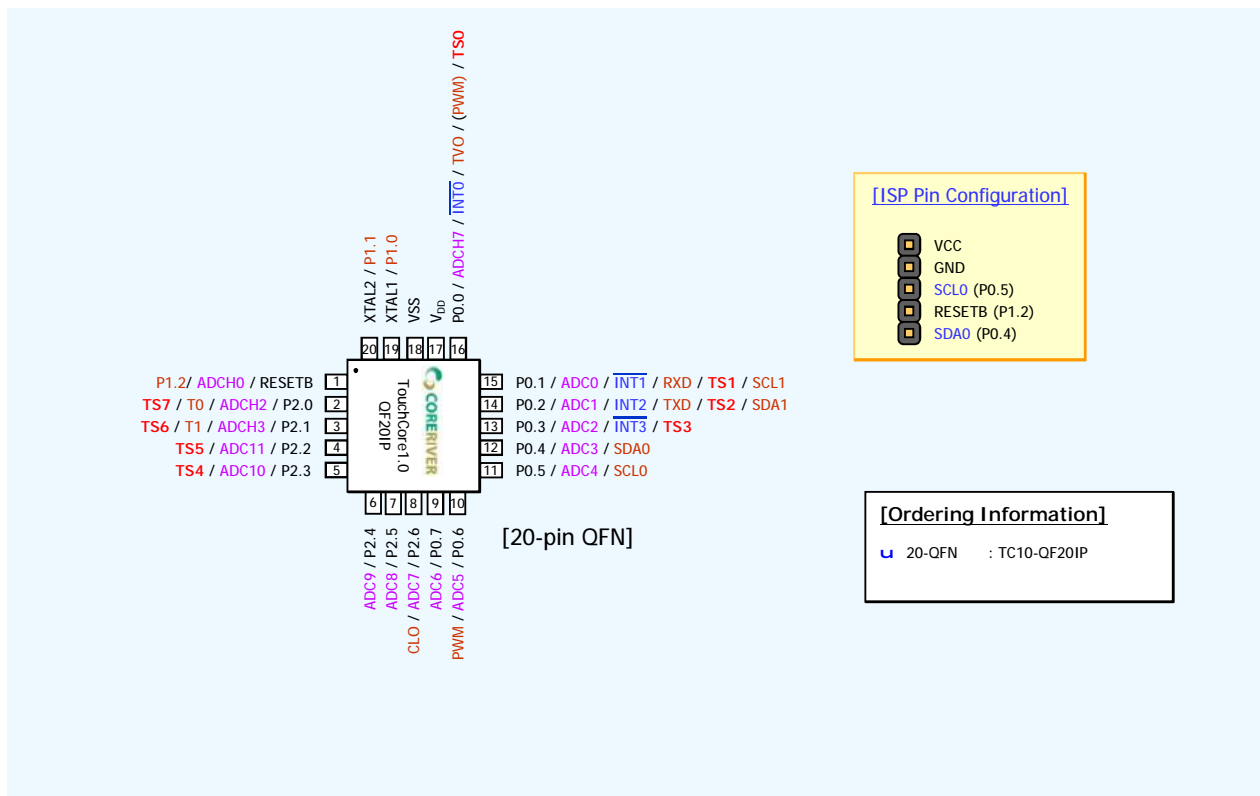
- 20-SOIC (Wide) : TC10-SO20IP
- 8-SOIC : TC10-SO8IP



### [ISP Pin Configuration]



## 4. Pin Configurations (2 of 2)

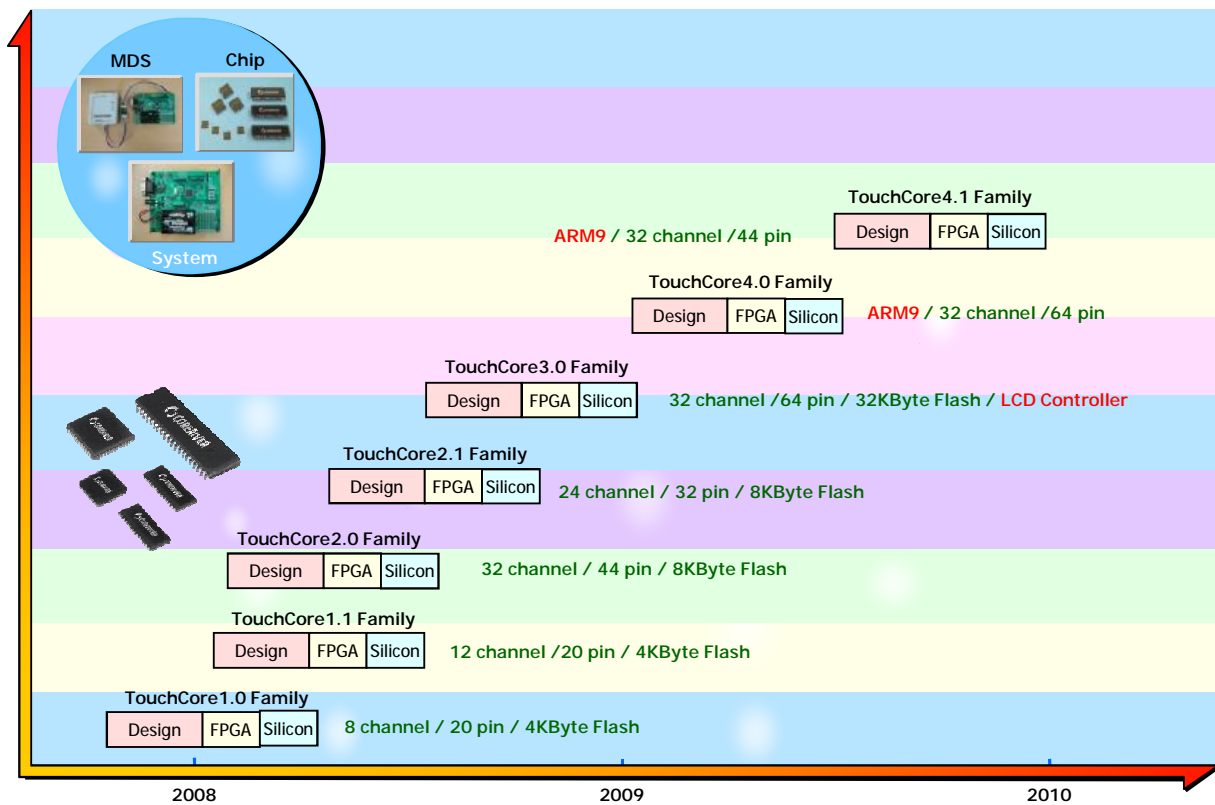


## 5. Pin Descriptions

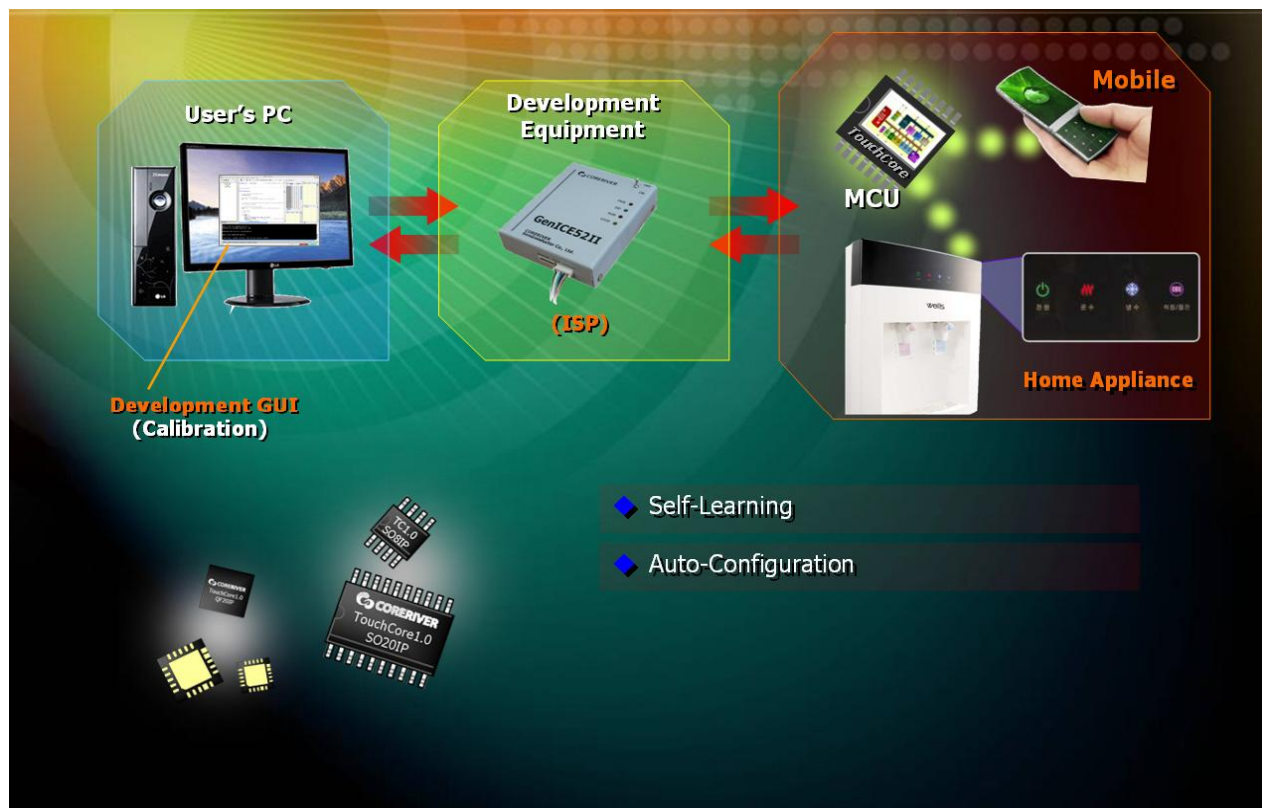
Symbol	Direction	Description	Share Pins
V <sub>DD</sub>	Input	Power Supply	-
V <sub>SS</sub>	Input	Ground	-
XTAL1 / P1.0	Input/Output	§ Crystal Input/Output (Default) § Bit Programmable with Schmitt Trigger - Optional Pull-up Control Enable - Open-drain Output - Push-pull Output	XTAL1 / P1.0 (Crystal Input)
XTAL2 / P1.1			XTAL2 / P1.1 (Crystal Output)
RESETB / P1.2	Input/Output	§ External Reset Input Signal (Default) § Bit Programmable - Optional Pull-up Control Enable - Open-drain Output - Push-pull Output	RESETB / P1.2 / ADCH0
P0[7:0]	Input/Output	§ Bit Programmable with Schmitt Trigger - Optional Pull-up Control Enable - Open-drain Output - Push-pull Output (Default)	P0.0 / ADCH7 / <u>TINT0</u> / TVO / (PWM) / TS0 P0.1 / ADC0 / <u>TINT1</u> / RXD / TS1 / SCL1 P0.2 / ADC1 / <u>TINT2</u> / TXD / TS2 / SDA1 P0.3 / ADC2 / <u>TINT3</u> / TS3 P0.4 / ADC3 / SDA0 P0.5 / ADC4 / SCL0 P0.6 / ADC5 / PWM P0.7 / ADC6
P2[6:0]	Input/Output	§ Bit Programmable with Schmitt Trigger - Optional Pull-up Control Enable - Open-drain Output - Push-pull Output (Default)	P2.0 / ADCH2 / T0 / TS7 P2.1 / ADCH3 / T1 / TS6 P2.2 / ADC11 / TS5 P2.3 / ADC10 / TS4 P2.4 / ADC9 P2.5 / ADC8 P2.6 / ADC7 / CLO



## 6. Roadmap of Touch Solution



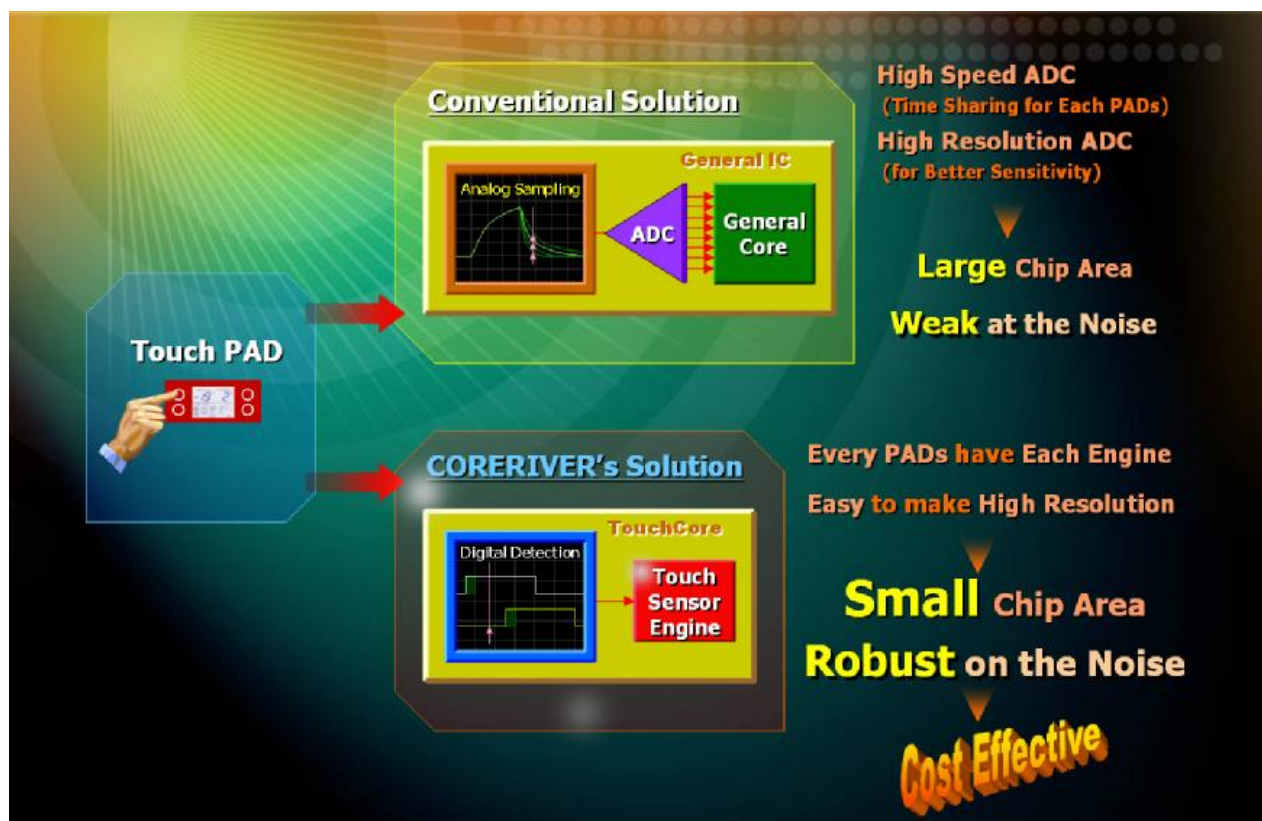
## 7. Development Tool Environment



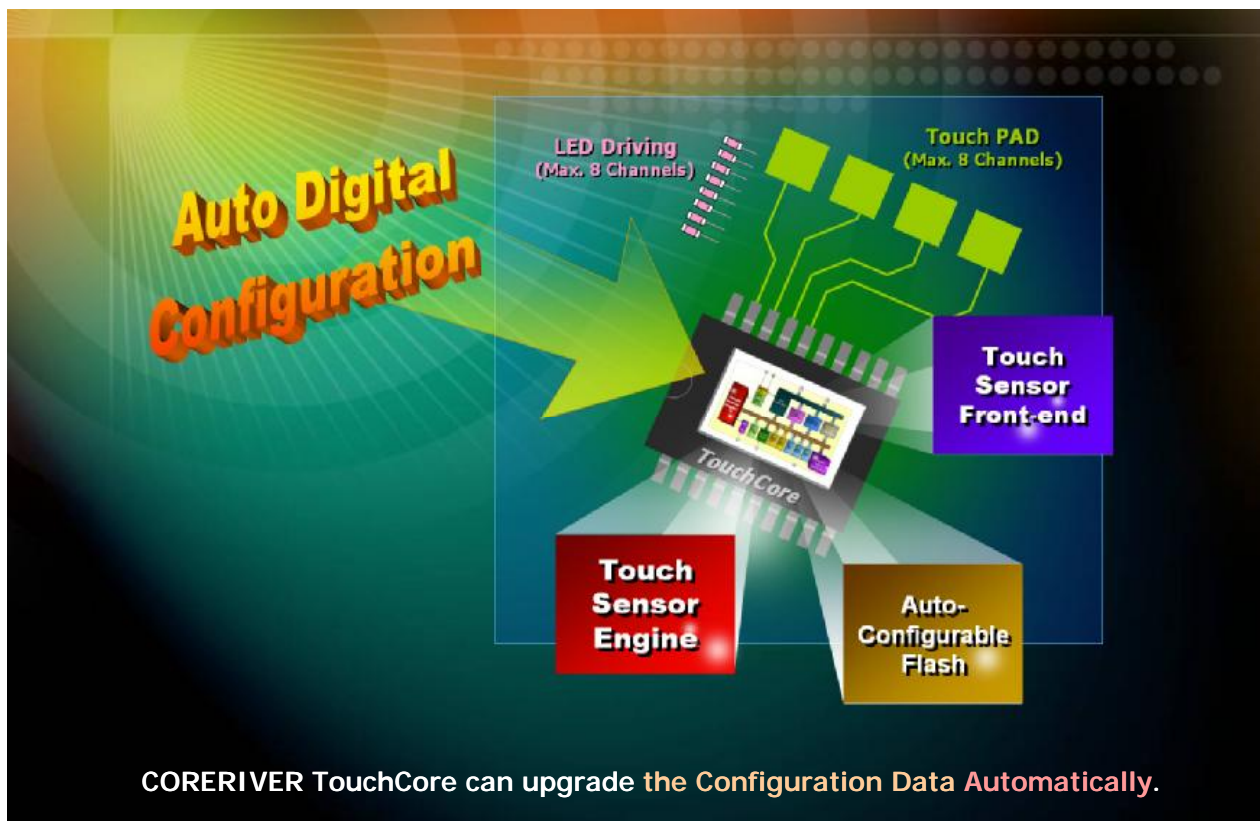
## 8. Comparison Table

	Conventional Devices	CORERIVER's TouchCore
Detection Type	Analog Detection	Digital Detection
Environmental Noise (Power, Humidity, Light, & Etc)	Weak at the Noise	Robust on the Noise
Cost	High	Low
External Component	R or C	Needless
Area Overhead	Large	Small
Touch Resolution	ON/OFF	Max. 256 level
Detection Speed	Slow	Fast
Available Touch PAD Type	Single	Single, Matrix, Complex
Power Consumption	Typ. 100uA	SNAP Mode Support (Typ. 6uA)

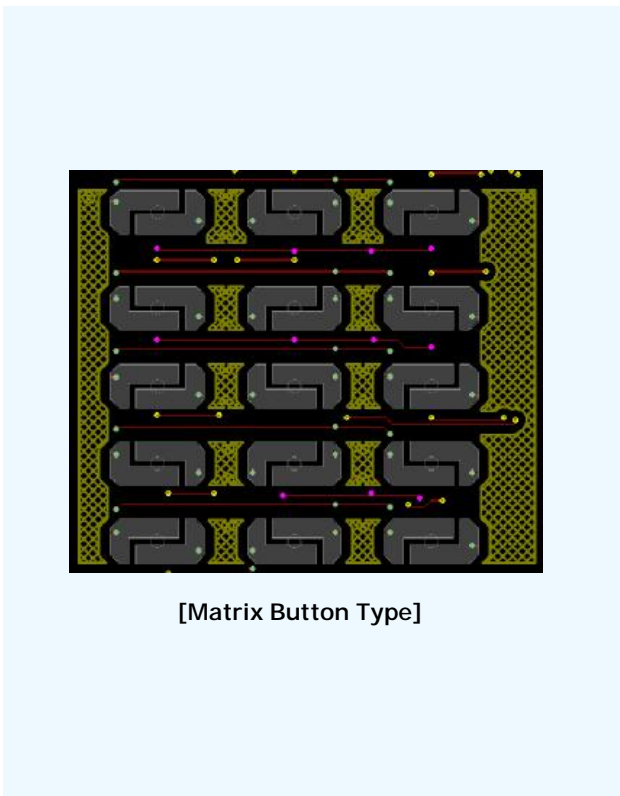
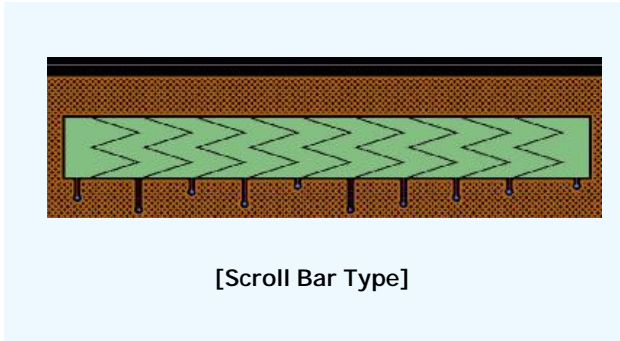
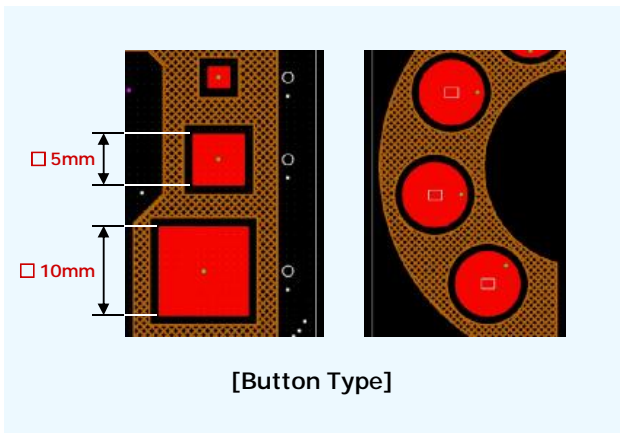
## 9. Strong Points : I. Digital Scheme



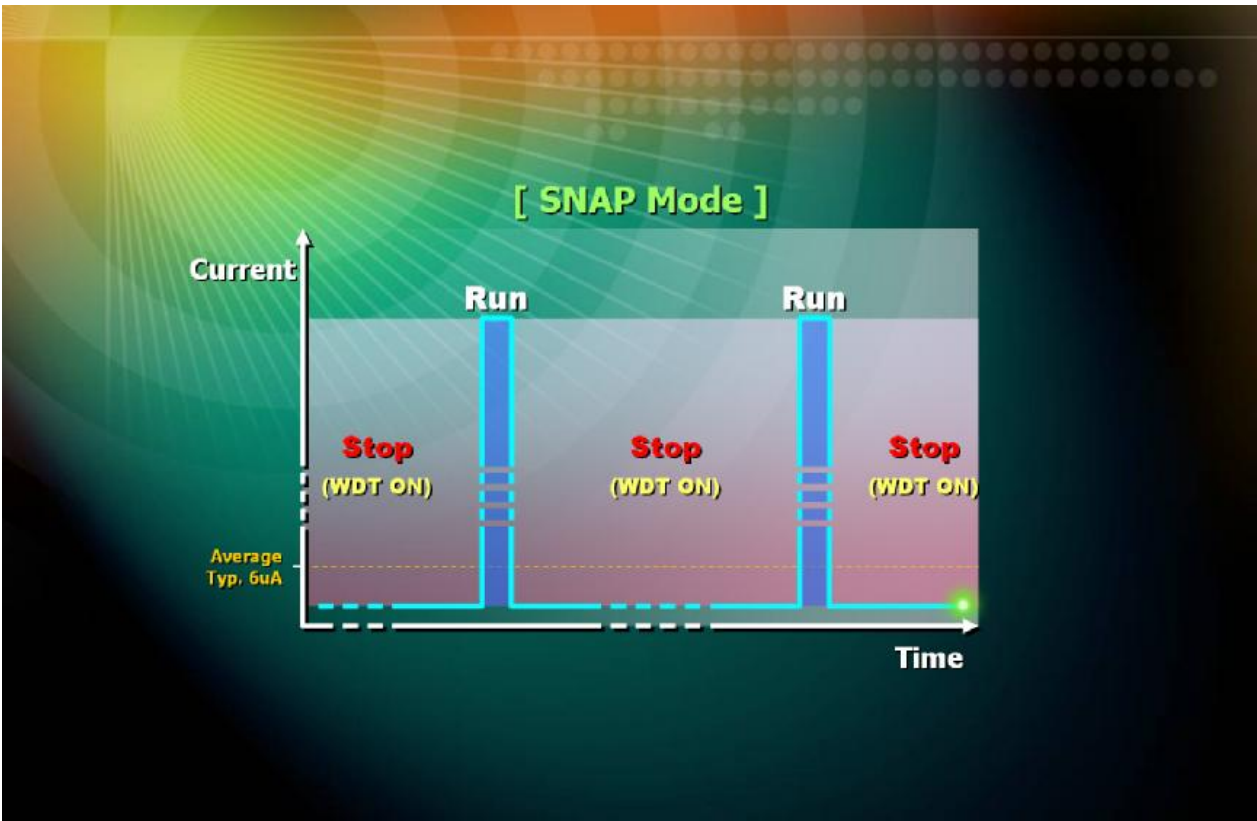
## 9. Strong Points : II. Flexibility



## 9. Strong Points : III. Various Touch PAD Types



## 9. Strong Points : IV. Low Power



## 10. Absolute Maximum Ratings

Items	Conditions	Ranges
Voltage on any pin relative to Ground	-	-0.5V to ( $V_{DD}+0.5V$ )
Voltage in $V_{DD}$ relative to Ground	-	-0.5V to 6.5V
Output Voltage	-	-0.5V to ( $V_{DD}+0.5V$ )
Output Current High	One I/O pin active	-25mA
	All I/O pin active	-100mA
Output Current Low	One I/O pin active	+30mA
	All I/O pin active	+150mA
Storage Temperature	-	-65 °C to +150 °C
Soldering Temperature	-	Peak 260 °C, 20 seconds within 5 °C of actual peak temperature



## 11. DC Characteristics

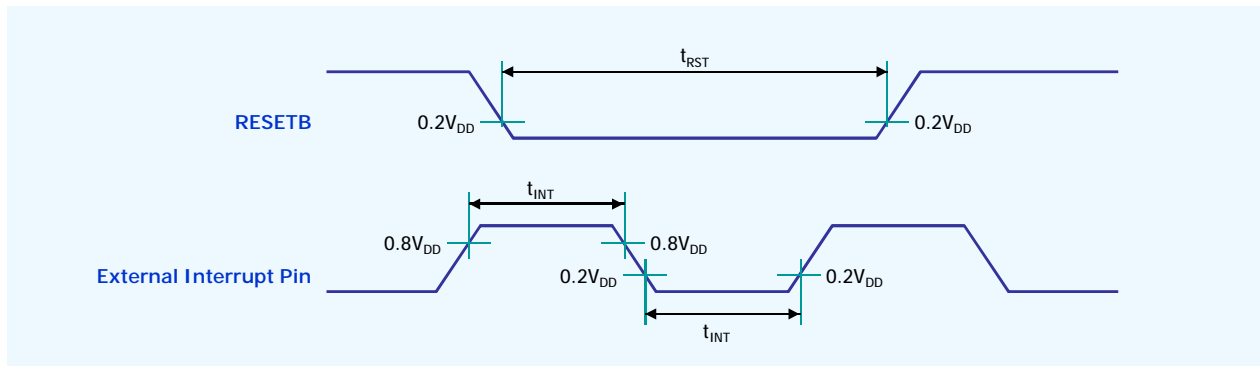
\* TA = -20 °C ~ +85 °C, V<sub>DD</sub> = 1.8V ~ 5.5V unless otherwise specified.

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Input Low Voltage	V <sub>IL1</sub>	RESETB, P0, P1, P2	V <sub>DD</sub> = 1.8V ~ 5.5V	-0.5	-	0.2V <sub>DD</sub> -0.1	V
	V <sub>IL2</sub>	XTAL1, XTAL2		-0.5	-	0.3V <sub>DD</sub>	
Input High Voltage	V <sub>IH1</sub>	RESETB, P0, P1, P2	V <sub>DD</sub> = 1.8V ~ 5.5V	0.2V <sub>DD</sub> +1.0	-	V <sub>DD</sub> +0.5	V
	V <sub>IH2</sub>	XTAL1, XTAL2		0.7V <sub>DD</sub>	-	V <sub>DD</sub> +0.5	
Output Low Voltage	V <sub>OL</sub>	All Pins	I <sub>OL</sub> = 20mA @V <sub>DD</sub> =5V (I <sub>OL</sub> = 3mA @V <sub>DD</sub> =2.2V)	-	-	0.3V <sub>DD</sub>	V
Output High Voltage	V <sub>OH</sub>	All Pins	I <sub>OH</sub> = -15mA @V <sub>DD</sub> =5V (I <sub>OH</sub> = -2mA @V <sub>DD</sub> =2.2V)	0.7V <sub>DD</sub>	-	-	V
	V <sub>OHP</sub>	All Pins ( Pull-up)	I <sub>OHP</sub> = -40uA @V <sub>DD</sub> =5V (I <sub>OHP</sub> = -15uA @V <sub>DD</sub> =2.2V)	0.7V <sub>DD</sub>	-	-	V
Input Leakage Current	I <sub>IL</sub>	All Pins except XTAL1 & XTAL2	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	-	-	±1	μA
Pin Capacitance	C <sub>IO</sub>	All Pins	V <sub>DD</sub> = 5V	-	10	-	pF

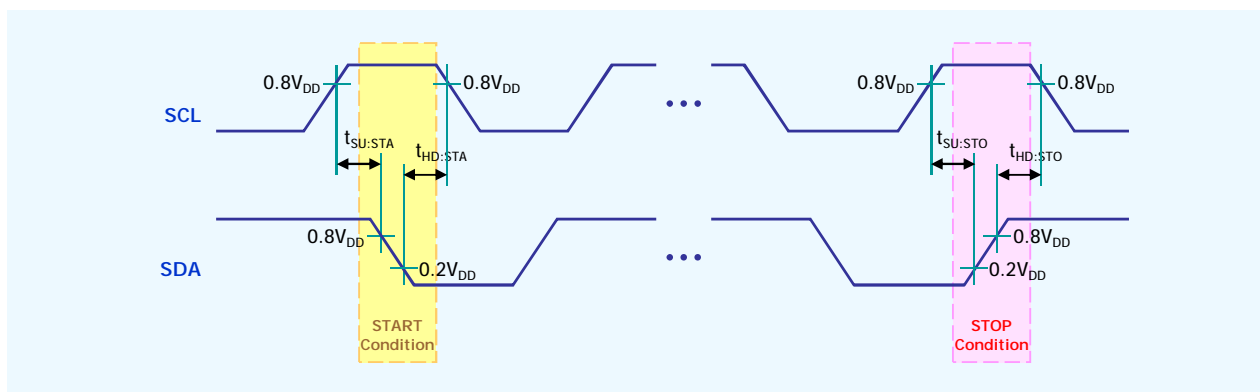
## 12. AC Characteristics

\* TA = -20 °C ~ +85 °C unless otherwise specified.

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Operating Frequency	F <sub>OSC</sub>	XTAL1, XTAL2	V <sub>DD</sub> = 5V ± 10%	1	-	24	MHz
			V <sub>DD</sub> = 3V ± 10%	1	-	12	
RESETB Input Width	t <sub>RST</sub>	RESETB	V <sub>DD</sub> = 5V ± 10%	24	-	-	F <sub>OSC</sub>
			V <sub>DD</sub> = 3V ± 10%	24	-	-	
External Interrupt Input Width	t <sub>INT</sub>	External Interrupt	V <sub>DD</sub> = 5V ± 10%	4	-	-	F <sub>OSC</sub>
			V <sub>DD</sub> = 3V ± 10%	4	-	-	

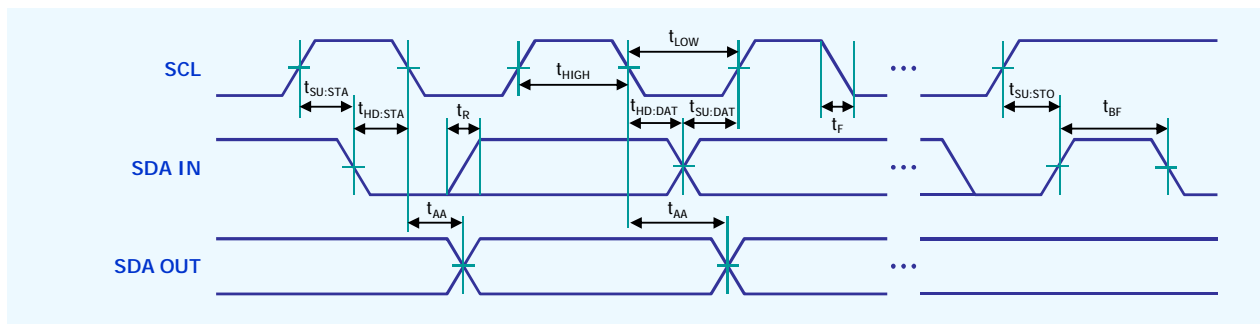


## 13. I2C Characteristics (1 of 2)



Symbol	Characteristic	Min	Max	Unit	Conditions	
$t_{SU:STA}$	Start condition setup time	100KHz mode	4,700	-	ns	Only relevant for repeated START condition
		400KHz mode	600	-		
$t_{HD:STA}$	Start condition hold time	100KHz mode	4,000	-	ns	After this period, the first clock pulse is generated
		400KHz mode	600	-		
$t_{SU:STO}$	Stop condition setup time	100KHz mode	4,700	-	ns	
		400KHz mode	600	-		
$t_{HD:STO}$	Stop condition hold time	100KHz mode	4,000	-	ns	
		400KHz mode	600	-		

## 13. I2C Characteristics (2 of 2)



Symbol	Characteristic	Min	Max	Units	Conditions	
$t_{HIGH}$	Clock high time	100KHz mode	4,000	-	ns	Minimum frequency : 1MHz
		400KHz mode	600	-		Minimum frequency : 5MHz
$t_{LOW}$	Clock low time	100KHz mode	4,700	-	ns	Minimum frequency : 1MHz
		400KHz mode	1,300	-		Minimum frequency : 5MHz
$t_{SU:DAT}$	Data Input setup time	100KHz mode	250	-	ns	
		400KHz mode	100	-		
$t_{HD:DAT}$	Data Input hold time	100KHz mode	0	-	ns	
		400KHz mode	0	900		
$t_{AA}$	Output valid from clock	100KHz mode	-	3,500	ns	
		400KHz mode	-	-		
$t_{BF}$	Bus free time	100KHz mode	4,700	-	ns	
		400KHz mode	1,300	-		
$t_R$	SDA and SCL rising time	100KHz mode	-	1,000	ns	The range of $C_b$ is from 10pF to 400pF.
		400KHz mode	$20 + 0.1C_b$	300		
$t_F$	SDA and SCL falling time	100KHz mode	-	300	ns	The range of $C_b$ is from 10pF to 400pF.
		400KHz mode	$20 + 0.1C_b$	300		

## 14. Package Dimensions : 20/8-SOIC

**[20-SOIC]**

Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.093	0.099	0.104	2.35	2.45	2.65
A <sub>1</sub>	0.004	0.008	0.012	0.10	0.20	0.30
b	0.014	0.016	0.019	0.35	0.42	0.49
D	-	0.450	-	-	11.43	-
E	0.291	0.295	0.299	7.40	7.50	7.60
H <sub>b</sub>	0.496	0.504	0.512	12.60	12.80	13.00
H <sub>e</sub>	0.404	0.411	0.419	10.26	10.45	10.65
L	0.057	0.058	0.060	1.43	1.48	1.53
L <sub>1</sub>	0.034	0.038	0.042	0.86	0.96	1.07
a	0°	-	8°	0°	-	8°
e	-	0.050 BSC	-	-	1.27 BSC	-
m	0.020	0.025	0.030	0.50	0.62	0.75

**Notes:**

- Dimension D Max. & S include mold flash or tie bar Burns.
- Dimension E<sub>1</sub> dose not include interlead flash.
- Dimension D & E<sub>1</sub> include mold mismatch and are determined at the mold parting line.
- Dimension B<sub>1</sub> does not include dambar protrusion/intrusion.
- General appearance spec. should be based on final visual inspection spec.

**[8-SOIC]**

Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.093	0.099	0.104	2.35	2.45	2.65
A <sub>1</sub>	0.004	0.008	0.012	0.10	0.20	0.30
b	0.014	0.016	0.019	0.35	0.42	0.49
D	-	0.150	-	-	3.81	-
E	0.150	0.153	0.157	3.80	3.90	4.00
H <sub>b</sub>	0.189	0.193	0.197	4.80	4.90	5.00
H <sub>e</sub>	0.234	0.239	0.244	5.95	6.07	6.20
L	0.038	0.043	0.048	0.97	1.08	1.2
L <sub>1</sub>	0.022	0.027	0.032	0.58	0.70	0.82
a	0°	-	8°	0°	-	8°
e	-	0.050 BSC	-	-	1.27 BSC	-
m	0.010	0.015	0.020	0.25	0.37	0.50

**Notes:**

- Dimension D & E include mold mismatch and are determined at the mold parting line.
- General appearance spec. should be based on final visual inspection spec.

## 14. Package Dimensions : 20-QFN

